# IFIC – SiWECAL activities: gluing and more

César Blanch, <u>Adrián Irles</u>, Jesús Márquez

\*AITANA group at IFIC – CSIC/UV



# Outline



#### Part1

▶ Draft of COB paper → noise comparison with BGAs → tomorrow!

#### Part 2

- Preparation for resistivity studies
- Dummy test to check viability of the tools (climatic chamber, ohmmeter) and qualitative results

#### Part 3

- Preparation of tools for gluing + first tests with PCBs
  - Aspiration plate in aluminum for sensor and pcb alignment (xy and z)
  - Use of an old batch of glue (EJ2189) and transparent fake wafers
  - The tools require small adaptations for the new CALICE FEV2 PCBs and the new ECAL-e flex PCBs

#### Part 4

PCB deformations tests after temperature/humidity cycles





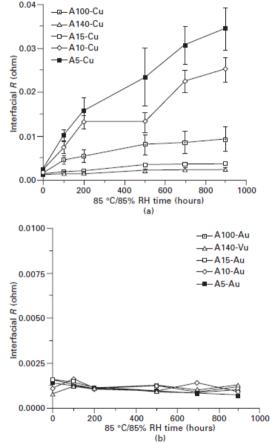
# **Part 2: resistivity evolution**

# **Resistivity of conductive epoxy**





- Several issues of sensor dellamination have been reported by SiW-ECAL
- Main suspects are the limited mechanical strength of the glue and the initial deformation of the PCBs
- However, we should not discard all other reasons
  - Conductive epoxys (silver balls) and aluminium can suffer oxydation, degrading the resistivity.

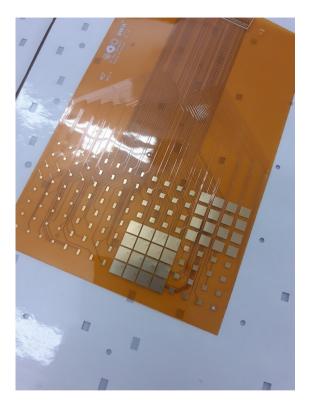


4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts, (b) on Au contacts, with (c) corresponding bulk resistivity variations.



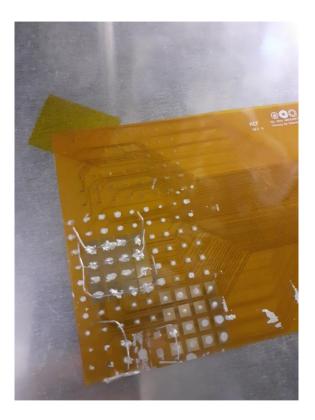
## Dummy tests using a flex pcb (FCAL)





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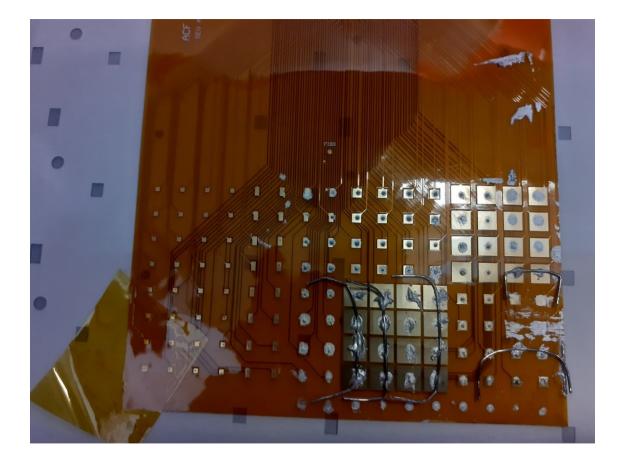


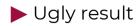
Use EJ2189 (default one in the last years) as soldering paste

• Solder wires to different pads (with resistivity measured)



# Curing in a climatic chamber



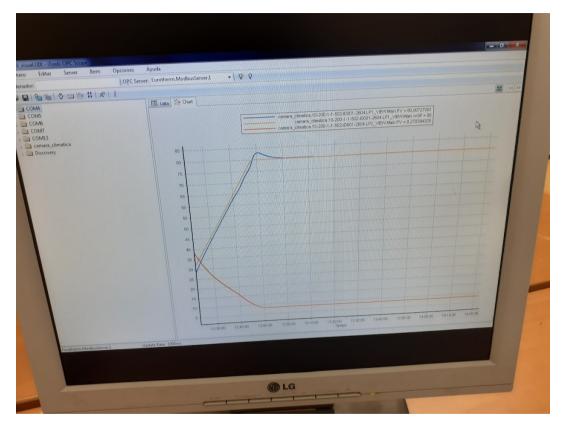


- But good enough to give qualitative results
- The resistivity between specific pads is measured after several humidity/temperature cycles performed



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# Curing in a climatic chamber



Follow the datasheet, minimal time is 80degrees 3h

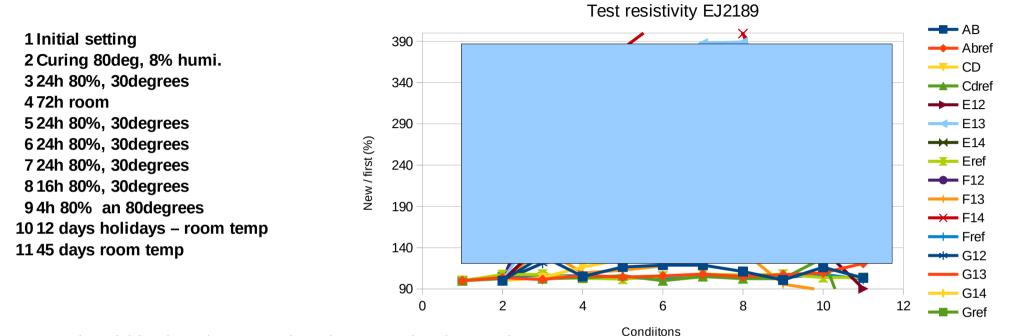
• Very low humidity during the full process (10%)

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## **Resistivity measurements**



We should look only at tendencies, not absolute values

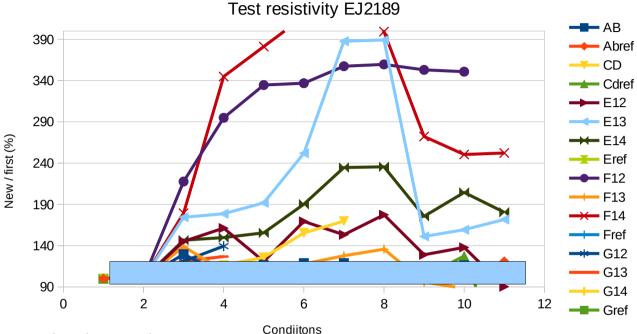
The G12-Gref (horizontal lines in 100%) are the reference values



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# **Resistivity measurements**

1 Initial setting 2 Curing 80deg, 8% humi. 3 24h 80%, 30degrees 4 72h room 5 24h 80%, 30degrees 6 24h 80%, 30degrees 7 24h 80%, 30degrees 8 16h 80%, 30degrees 9 4h 80% an 80degrees 10 12 days holidays – room temp 11 45 days room temp



We should look only at tendencies, not absolute values

- ▶ The G12-Gref (horizontal lines in 100%) are the reference values
- Resistivity increase after each humidity cycle



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# **Resistivity measurements**

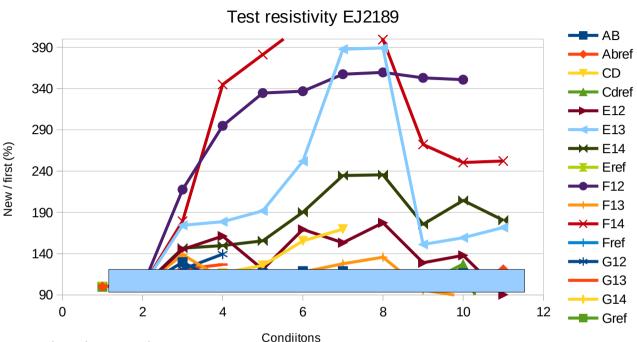
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▶ We should look only at tendencies, not absolute values

- ▶ The G12-Gref (horizontal lines in 100%) are the reference values
- Resistivity increase after each humidity cycle

Step 9: Resistivity decreased after a heat cycle (with high humidity)  $\rightarrow$  re-curing?

• The minimal requirements in the datasheet should be seen as the very minimum Irles A.,



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#### to-do

- This is simply an exercise involving a fair amount of bricolage...
- A proper measurement is on preparation:
  - Using new glue batches (H20E and EJ2189)
  - Using specifically designed flex PCBs (w.i.p. by Yan-FCAL) and dummy silicon sensors (with the same type of aluminum plating that the real sensors)
  - Using proper tools for glue dispensing (robot or stencil...)
  - Using cold plasma gun to clean the sensors before
  - Systematic measurements and comparisons
- Lots of work which require restructuring of the lab and the new postdoc to arrive.. w.i.p.





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Extra – under consideration: mechanical pull tests (with IJCLab) and irradiation tests with neutrons (in nTOF NEAR)



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# Part 3: gluing training

# Glue

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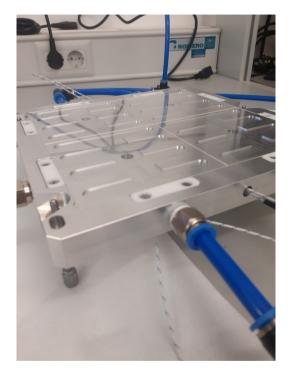


• New equipment!



## Fake wafers -xy alignment







Alignment of fake transparent sensors

• 500um



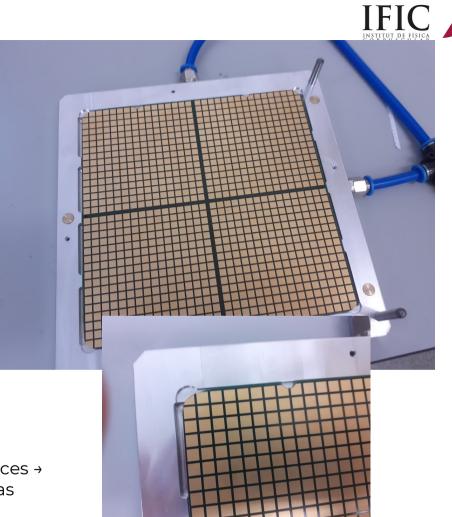
# PCB -xy alignment



Alignment of the PCB

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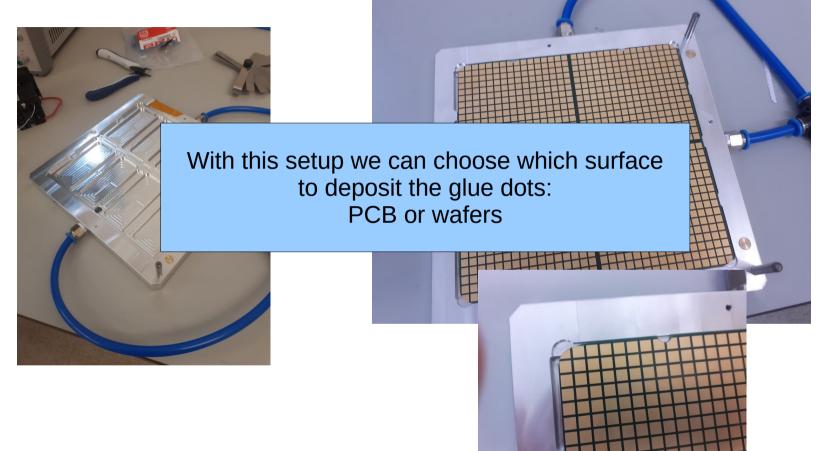
- Design of the plates optimized to FEV2 & tolerances → the FEV12 seems to be slightly larger. The PCB has been machined to fit in the plate
- PCB without components





## **PCB -xy alignment**



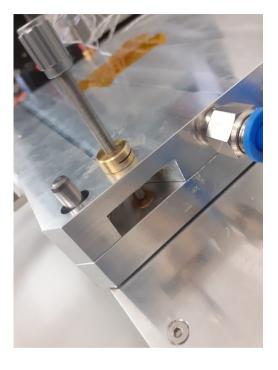




## **Z-alignment**







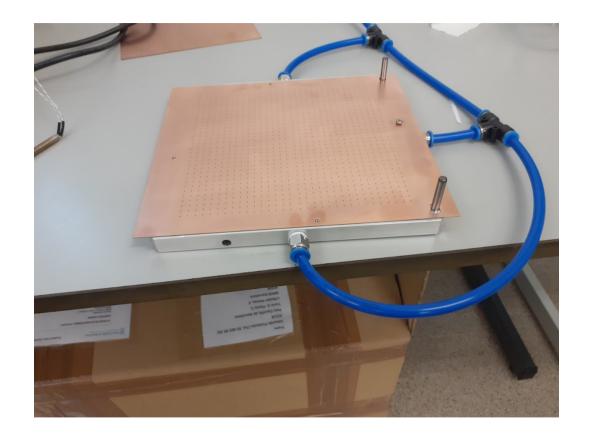
Tuneable for each use, using precision 3 micrometric screws together with feeler gauges

Z-alignment performed at 150um (separation between wafer and the pcb)



## **Glue repartition**





#### Stencil

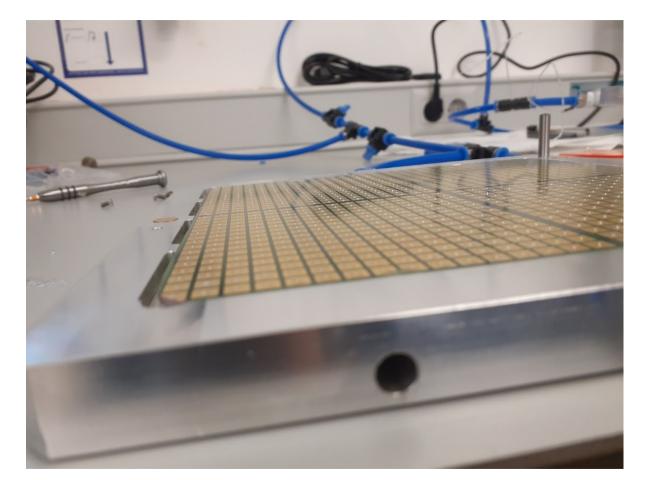
- 500um copper plate
- Holes of 0.8 or 1.2 mm diameter
- Stencil is a nice solution to keep the developments ongoing. Final solution should a robot.





## **Glue repartition**





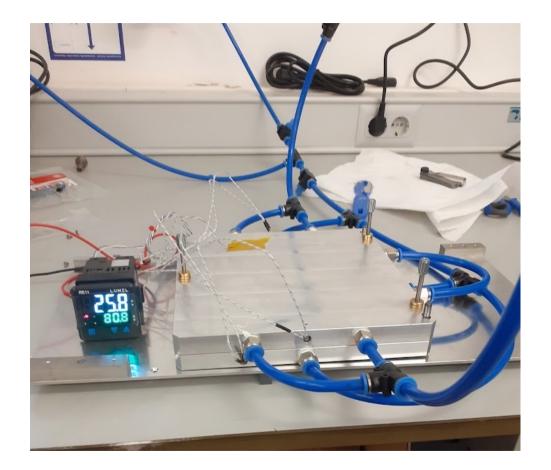
For the first try, we only add glue in 3 of the 4 sectors



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curing





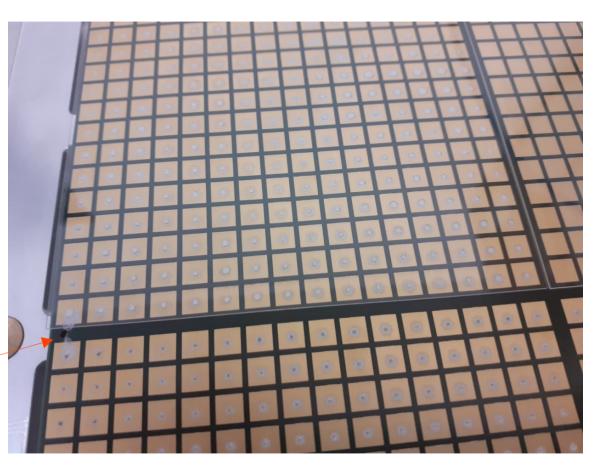
- ▶ 4 resistors (2 per aspiration plate)
- ▶ 80 degrees during 12h
  - + full weekend at room temp



#### results



- Only one wafer glued (up left in the photo
  - Still small adjustments on x-y the alignment needed (but seem straightforward)
- The z-alignment seems improvable
  → more amount of glue per dot needed
  - A new test is done with 1.2mm diameter holes instead
  - This is to be better defined with the gluing robot and dosification system
- Some glue spread around PCB holes -(due to the aspiration)





#### Summary & next steps



- > The basic design of the tools and the procedure has been validated
- ▶ New FEV2 are needed → the
- Fine tunning needed to optimize the alignment
- Close collaboration with mechanical engineering services at IFIC (César as liason).
- Stencil approach to be overruled by robot and volumetric dosification system (already ordered)
  - Precifluid & POLY DISPENSING SYSTEMS









# **Part 4: PCB deformations**

#### tools

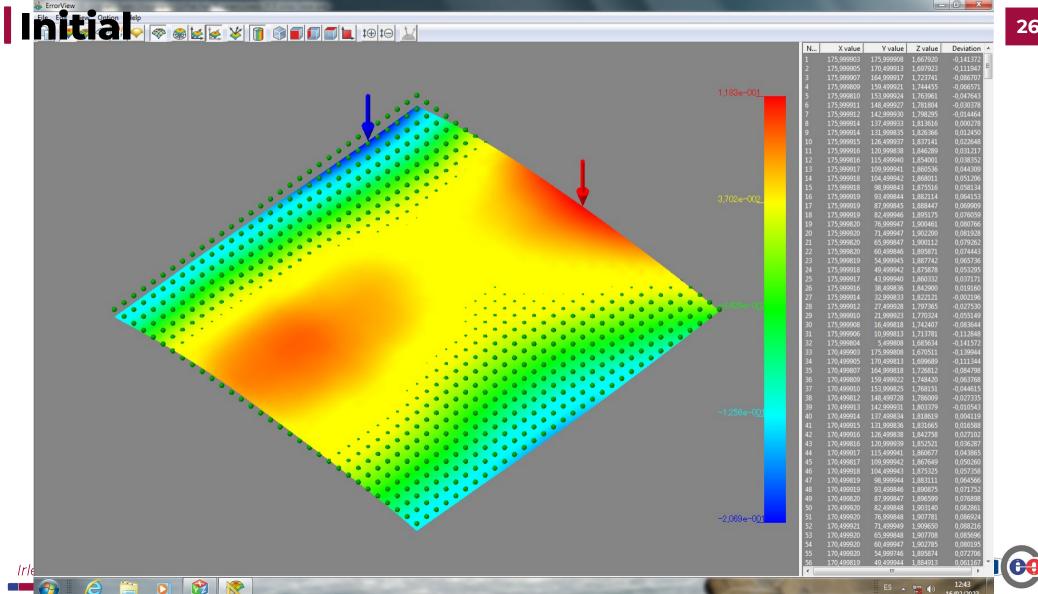


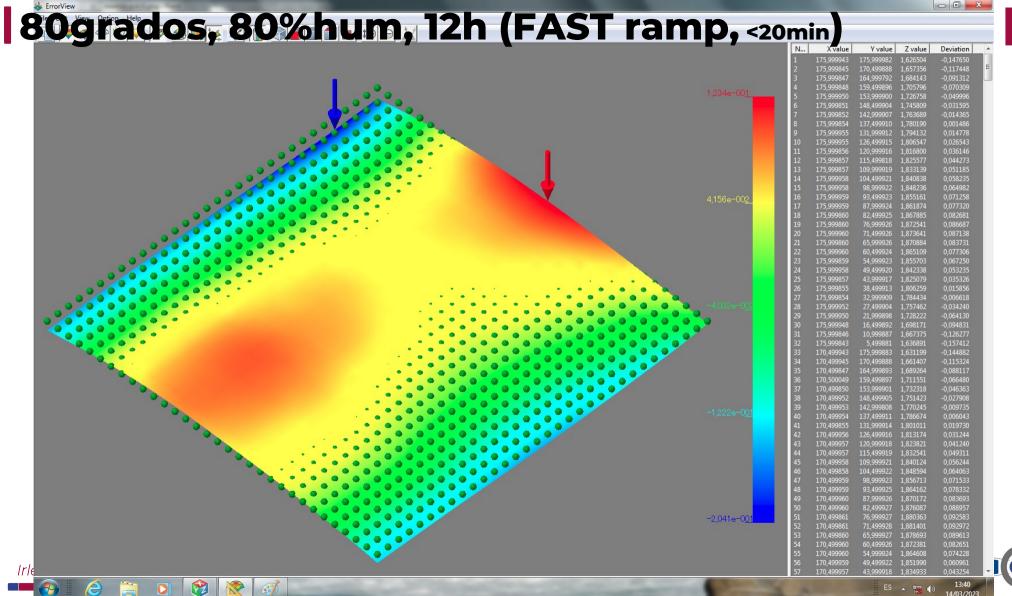
#### FEV 12 naked

- Not the same that we used for the glue tests.
- Climatic chamber
- ▶ Tool for z-axis characterization via optical focus
  - Mitutyo Quick Vision Accel, Modelo 808
  - https://www.mitutoyo.com/webfoo/wp-content/uploa ds/2118\_Quick\_Vision.pdf
- Several 12-24h cycles with 80-100 degrees, 10-80% humidity









#### results



- Basically no extra deformation observed after the cycles
  - But an initial +120um, -200um deformation from the middle plane
- Curing at 100degrees may not be an issue at all.
  - Tests done without sensors/components!
- ▶ Would this PCB have been used for gluing sensors?
  - The aspiration plate was capable of support it removing the deformation....
- ▶ However, the component soldering is done in more extreme conditions
  - 200-250 degrees with very quick peaks of temperature. Studies to be done...







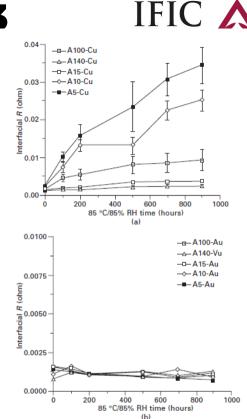




# Tests to be done January-April 2023

- We have purchased a set of dummy substrates with aluminum and gold bath (as the Hammatsu sensors)
  - Delivery in ~ January
- We have orderd the epoxys (still waiting for the note on the gold based).
  - Delivery in January-February
- Yan is designing a special kapton fanout to be glued to the dummy sensors and perform resitance measurements of the glue dots.
  - Using a precision ohmemetre to measure mOhms.
  - Production/delivery?March?
- We are getting trained in the use of a climatic chamber here at IFIC: the idea is to tests the different glues and surfaces after several humidity cycles and check the resistivity.

Also access to a x-ray machine for a "visual" inspection.



4.9 Ag ICA contact resistance changes at 85/85: (a) on Cu contacts, (b) on Au contacts, with (c) corresponding bulk resistivity variations.

Bibliography reference on epoxy+silver glues performance (attached to the agenda)



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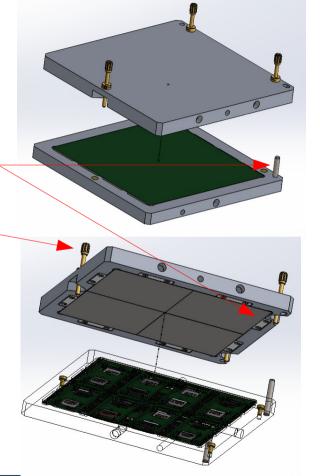
# aspiration plates design

- Sandwich-maker style
- Two aspiration plates
  - One for the wafers
  - One for the PCBs (with components in it)
- Alignment in x-y done by the aspirations themselves and pivot tools
- Alignment in z done with micrometric screws
- To deal with the PCB thickness tolerances (of possible hundreds of um)



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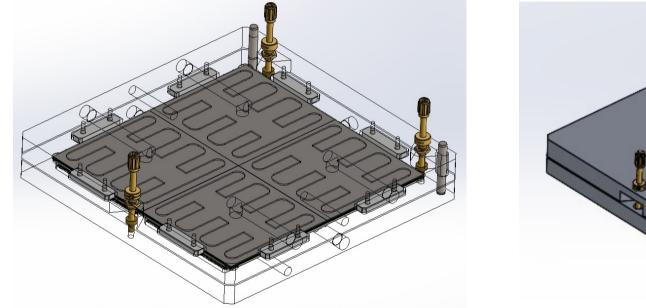


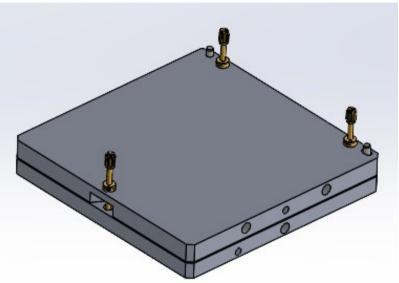




## Activity 1 – aspiration plates design







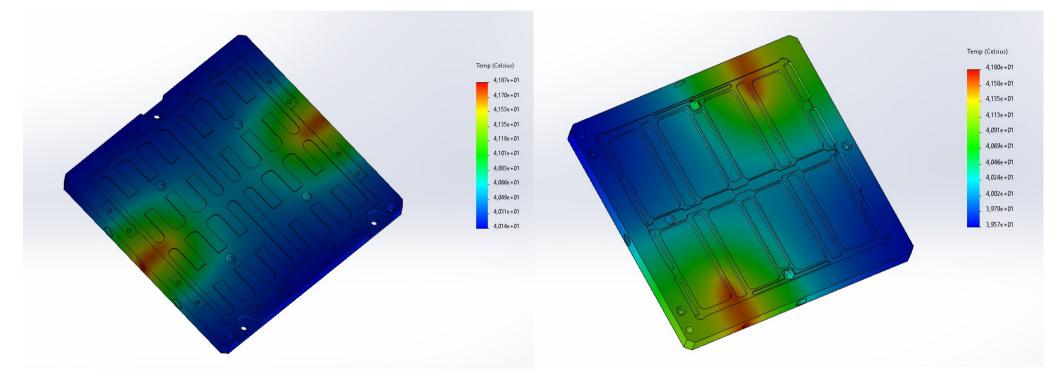




# Activity 1 – aspiration plates design



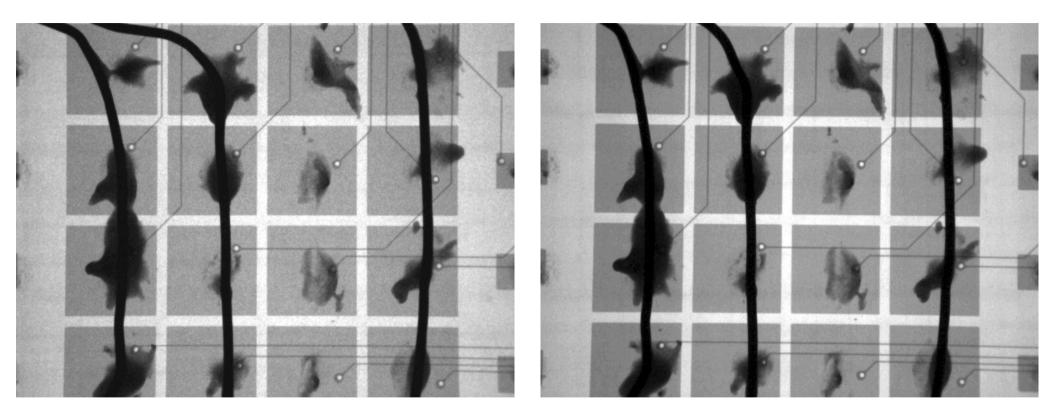
Also thermal curing using resistance and APDs for temperature control





## X-rays exploration





Before curing

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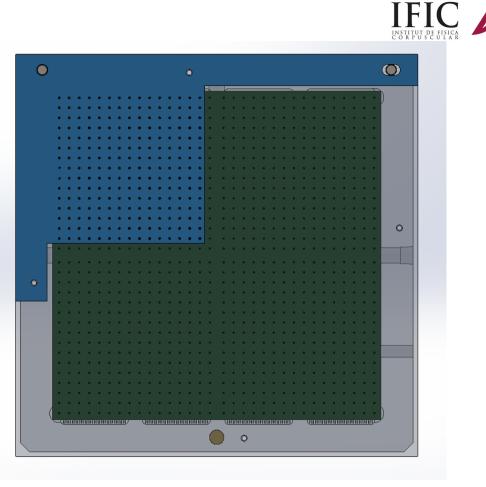
After all cycles

I don't appreciate any difference...



#### Follow up tests

- Last drops of EJ2189 glue.
- New stencil for only one quarter
  - 1.2mm holes instead of 0.8
- Z-alignment performed at 150um
- Warm-up from 25 to 80 degrees took 1h15min
  - After that time, we remove the zaxis limitations of 150um
  - The plates did not move







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